

SPECIFICATION AMENDMENTS

Replace the paragraph at page 48, lines 4-11 with the following paragraph:

Thereafter, through-hole 768 is formed through insulative base 740 and adhesive 792 and exposes the second enlarged circular region of routing line 732. Through-hole 768 is formed in essentially the same manner as through-hole 168. Namely, the laser drills through and removes portions of insulative base 740 and adhesive 792 within the surface area of opening 790, thereby effecting a pattern transfer of opening 790 through insulative base 740 and adhesive 792 to routing line 732. A brief cleaning step can then be applied to remove oxides and debris that may be present on the exposed portion of routing line 732.